

**PCN Number:** 20160331001 **PCN Date:** 4/8/2016

**Title:** Qualification of CFAB as an additional wafer fab site option for select devices in LBC5 process technology

**Customer Contact:** [PCN Manager](#) **Dept:** Quality Services

**Proposed 1<sup>st</sup> Ship Date:** 7/8/2016 **Estimated Sample Availability:** Date provided at sample request.

<b>Change Type:</b>		
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Assembly Materials
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Wafer Fab Site	<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process
	<input type="checkbox"/> Part number change	

**PCN Details**

**Description of Change:**

This change notification is to announce the qualification of CFAB as an additional wafer fab site option for the LBC5 devices listed in the product affected section of this document.

Current			Additional		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
DP1DM5	LBC5	200 mm	CFAB	LBC5	200 mm

The LBC5 process technology has been running successfully in production at CFAB since 2012.

**Reason for Change:**

Continuity of Supply

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None


**Changes to product identification resulting from this PCN:**

Current			
Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New			
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
CFAB	CU3	CHN	Chengdu



Sample product shipping label (not actual product label)



MADE IN: Malaysia  
2DC: 20

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT: 39  
ITEM: LBL: 5A (L) TO: 1750

(1P) SN74LS07NSR  
 (Q) 2000 (D) 0336  
 (31T) LOT: 3959047MLA  
 (4W) TKY (1T) 7523483S12  
 (P)  
 (2P) REV: (V) 003317  
 (20L) CSO: SHE (21L) CCO: USA  
 (22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

CXD9981TNDDV	TAS5342LAADDVR	TAS5614ADKD	TAS5708PHPR
CXD9981TNDDVR	TAS5352ADDV	TAS5614ADKDR	TAS5710PHP
CXD9981UTNDDV	TAS5352ADDVR	TAS5614APHD	TAS5710PHPR
CXD9981UTNDDVR	TAS5613ADKD	TAS5614APHDR	TPA3251D2DDV
TAS5342ADDV	TAS5613ADKDR	TAS5708LPHP	TPA3251D2DDVR
TAS5342ADDVR	TAS5613APHD	TAS5708LPHPR	TPS65149RSHR
TAS5342LAADDV	TAS5613APHDR	TAS5708PHP	TPS65155RKPR

**Qualification Report**

**Qualification of LBC5 Process Technology at CFAB  
Approved 03/02/2012**

**Die Attributes**

Attributes	Process QBS : TAS5613APHD Approved: 3/2/2012	Process QBS: DRV8813A0PWP Approved: 3/2/2012	Process QBS: SN8C0183PWP Approved: 3/2/2012
Wafer Fab Site	CFAB	CFAB	CFAB
Wafer Fab Process	LBC5	LBC5	LBC5
Wafer Diameter	200mm	200mm	200mm

- QBS: Qual By Similarity
- Qual Device TAS5613APHD and SN8C0183PWP are qualified at LEVEL3-260C
- Qual Device DRV8813A0PWP is qualified at LEVEL1-260C

**Qualification Results**

**Data Displayed as: Number of lots / Total sample size / Total failed**

Type	Test Name / Condition	Duration	Qual Device: TAS5613APHD	Qual Device: DRV8813A0PWP	Qual Device: SN8C0183PWP
AC	Autoclave 121C	96 Hours	3/77/0	3/77/0	-
ED	Electrical Characterization	Per Datasheet Parameters	3/Pass	3/Pass	3/3/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/77/0	-	-
HBM	ESD - HBM	1500 V	3/21/0	1/3/0	-
CDM	ESD - CDM	250 V	3/15/0	1/3/0	-
HTOL	Life Test, 155C	240 Hours	3/77/0		3/77/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/77/0	-	-
LU	Latch-up	(per JESD78)	3/6/0	1/6/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/77/0	3/77/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles  
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

<b>Location</b>	<b>E-Mail</b>
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>